

## AMENDMENTS TO THE CLAIMS:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1. (currently amended) A method comprising bonding a chip module in a card body with an adhesive comprising at least two adhesive layers (i) and (ii), ~~the at least two layers (i) and (ii) of the adhesive film differing chemically from one another, wherein the adhesive layer (i) exhibits high bonding compatibility with epoxy materials and/or polyimides, wherein the adhesive layer (ii) is based on polyurethanes and/or rubbers, wherein the adhesive layer (ii) bonds the adhesive layer (i) to the card body.~~

Claim 2. (currently amended) The method of claim 1, wherein ~~an adhesive of the adhesive layer the adhesives of layers (i) is a~~ and/or (ii) are pressure sensitive adhesives.

Claim 3. (currently amended) The method of claim 1, wherein ~~the adhesive layer (i) exhibits high bonding compatibility with epoxy materials and/or polyimides and layer (ii) exhibits high bonding compatibility with polycarbonate, polyethylene, polypropylene, acrylonitrile-butadiene-styrene copolymer plastics, polyethylene terephthalate and/or polyvinyl chloride.~~

Claim 4. (original) The method of claim 1, wherein layer (i) is based on thermoplastic polymers.

Claim 5. (original) The method of claim 4, wherein the thermoplastic polymers are selected from the group consisting of thermoplastic polymers based on polyesters, polyamides, copolyesters and/or copolyamides.

Claim 6. (canceled)

Claim 7. (currently amended) The method of claim 1, 6, wherein layer (ii) is based on synthetic rubbers.

Claim 8. (canceled)

Claim 9. (currently amended) A method comprising bonding a chip module in a card body with an adhesive comprising at least two adhesive layers (i) and (ii), wherein the adhesive layer (i) exhibits high bonding compatibility with epoxy materials and/or polyimides. The method of claim 8, wherein layer (ii) is based on a heat-activatable system composed of an elastomer and at least one reactive resin, wherein the elastomer is composed of at least one of rubbers, polychloroisoprenes, polyacrylates, nitrile rubbers and/or epoxidized nitrile rubbers and/or the reactive resin is composed of at least one of phenolic resins, epoxy resins, melamine resins and/or resins with

isocyanate function, wherein the adhesive layer (ii) bonds the adhesive layer (i) to the card body.

Claim 10. (original) The method of claim 1, wherein between layer (i) and layer (ii) there are one or more further layers.

Claim 11. (original) The method of claim 10, wherein the one or more further layers comprise one or more primer, barrier and/or carrier layers.

Claim 12. (currently amended) An adhesive unit consisting of a card body, an adhesive film and a chip module, wherein the adhesive film comprises at least two adhesive layers (i) and (ii), wherein the adhesive layer (i) exhibits high bonding compatibility with epoxy materials and/or polyimides, wherein layer (ii) is based on polyurethanes and/or rubbers, wherein the adhesive layer (ii) is bonded to the adhesive layer (i) and the card body the at least two layers (i) and (ii) of the adhesive film differing chemically from one another.